Power Matters.[™]



Radiation-Tolerant FPGA Update

Ken O'Neill Director of Marketing, Space and Aviation

Company Overview



- Leading-edge semiconductor solutions differentiated by:
 - Performance
 - Reliability
 - Security
 - Power
- Solid financial foundation
 - FY2017 revenue: \$1.8B
 - 4800 employees today
- Major focus products
 - FPGAs and ASIC
 - Timing and OTN
 - Mixed-signal and RF
 - Switches and PHYs
 - Storage controllers
 - Discretes and integrated power solutions



Microsemi's Space Pedigree





- Developing space solutions for six decades
- Proven track record of innovation, quality, and reliability

Broad Solutions Portfolio

• Power, mixed-signal, and digital for bus and payload applications

Expanding our Product Portfolio through Continuous Innovation

A Partner for the Long Run

• 60-year space heritage



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Agenda

- RTG4 radiation tolerant FPGAs
 - Product overview
 - CQ352 package
 - Qualification and reliability update
 - Software, IP and solutions
 - Radiation testing, results and schedule
- Mixed Signal
- Clocks and Oscillators
- Power Products



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RTG4 High-Speed RT FPGAs



RTG4 mitigates the risks of ASICs and SRAM FPGAs, and has 20x improvement in signal processing throughput



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RTG4 Product Overview

Resources	RT4G150		
Logic Elements (TMR Register + 4-Input C Logic)	151,824	151,824	
18x18 Multiply-Accumulate Blocks	462	462	
RAM Mbits (1.5 Kbit and 24 Kbit Blocks, with ECC)	5.2	5.2	
UPROM Kbits	381	381	
DDR2/3 SDRAM Controller (with ECC)	2 x 32	0	
PCI Express Endpoints	2	1	
Globals	24	24	
PLLs (Rad Tolerant)	8	8	
SpaceWire Clock and Data Recovery Circuits	16	4	
User IO (excluding SERDES)	720	166	
SERDES lanes (3.125 Gbps)	24	4	
Hermetic, Ceramic Packages			
CG1657 (Ceramic Column Grid Array, Six Sigma Columns) LG1657 (Ceramic Land Grid Array, No Solder Termination) CB1657 (Ceramic Ball Grid Array, For Prototyping Only)	Available Now		
CQ352 (Ceramic Quad Flat Pack)		Samples Now Flight units in July '18	





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CQ352 Package Update

- CQ352 package features:
 - 166 MSIO supporting up to 3.3 V
 - 4 SpaceWire ports
 - 4 SerDes transceivers supporting EPCS and PCIE
 - Embedded Presidio Precious Metal Electrode (PME) 0508 decoupling capacitors
- Package size and weight: 48 mm x 48 mm x 2.25 mm, 32 g
- Pin assignment table and package drawing available on the Microsemi website
- Engineering silicon available today
- Flight units qualified to Mil Std 883B will be available July 2018 (to lead time)
- Software support now available in Libero SoC v11.7 SP3 and later





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RTG4 Qualification Status – QML Class Q Completed!

- QML Class Q qualification completed
 - Mil Std 883 Class B qualification completed
 - SMD has been approved and is posted on DLA web site
 - RTG4 FPGAs (B, E flow) can be ordered using, and will be dual marked with, 5962-16208xxyyy part number
 - SMD numbers on Microsemi web site in <u>DLA Cross Reference Guide</u>
- QML Class V qualification pending
 - Completion target: mid 2018
 - Qualification uses RT4G150 in 1657-pin LGA / CCGA package
 - 45 units from 1 wafer lot

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- 4,000 hour life test was completed in 2017
- Qualification data has been submitted to DLA
- EV-flow flight units are available prior to official QML class V qualification

RT4G150 1657-CCGA RT4G150-CG1657B 5962-1620801QXF RT4G150-1CG1657B 5962-1620802QXF RT4G150-CG1657E 5962-1620805QXF RT4G150-1CG1657E 5962-1620806QXF 1657-LGA RT4G150-LG1657B 5962-1620803QZC RT4G150-1LG1657B 5962-16208040ZC RT4G150-LG1657E 5962-16208070ZC RT4G150-1LG1657E 5962-1620808QZC



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RTG4 Reliability Testing Highlights

- Mil Std 883 Class B and QML class Q Qualification:
 - 3 wafer lots, 54 units successfully completed 1,000-hour group C life test at $T_J \ge 125 \text{ °C}$
 - All units continued additional life test exceeding MIL-STD-883B requirements: 54 units were functional during and after 4,000-hour life test at T_J ≥ 125 °C
- Additional reliability testing
 - Total 969 RTG4 FPGAs completed > 420,000 device-hours of life testing, 0 failures
- ESD Class 1A
 - V_{DDAIO} passed 250 V, other pins passed 2000 V
- Extensive reliability data collected for commercial 65nm Flash process from UMC
 - Overall 65nm product FIT rate calculated < 3.11 FIT (60% confidence level, EA = 0.7eV)
- See <u>RT0001: Microsemi FPGA and SoC Products Reliability Report</u>



RTG4 High Temperature Retention

- Product retention 20 years at $T_{J} \le 115^{\circ}$ C, or 10 years at $T_{J} \le 125^{\circ}$ C
- Zero failures during Non-Volatile Memory Cycling Endurance testing
 - 54 units, from 6 wafer lots
 - 470+ program / erase cycles (exceeds datasheet limits),
 - Followed by 1,000 hour high temp life test

Tj(C)	HTR (Years)
90	20
95	20
100	20
105	20
110	20
115	20
120	14
125	10
130	7.2
135	5.3
140	3.9
145	2.8
150	2.1





Libero SoC Software Highlights

- 11.7 SP3 Released in January 2017
 - CQ352 package support: STD speed grade, advance timing data
- 11.8 Released in March 2017
 - Include Synplify Pro ME (L2016.09M-2), which does not infer feed-through Write mode
- 11.8 SP1 Released August 2017
 - DirectC and .DAT file generation for RTG4 inflight programming (DirectC tool is free of charge)
- 11.8 SP2 Released November 2017
 - Adjustments to LSRAM X9 and X12 modes
- 11.8 SP3 Released February 2018
 - Bitstream detection of DEVRST_N assertion during programming
 - SRAM ECC simulation enhancements
 - Permanent programming enabled (One-Time Programmable mode)
 - Enhancements to Min Delay Violation repair
- 11.8 SP4 expect to release July or August 2018



RISC-V Open Instruction Set Architecture

- Free and open Instruction Set Architecture (ISA)
 - 32-bit instructions, optional 16-bit compressed instructions
 - 32-bit, 64-bit, and 128-bit address-space options
 - Quad floating point, virtualization, many cores, heterogeneous computing
- RISC-V is <u>not</u> an on open-source processor: it is an ISA <u>specification</u>
 - Covered under the Berkeley Software Distribution (BSD) open source license





RISC-V for **RTG4**

- RISC-V software tools
 - GNU GCC, binutils, newlib stdc library, gdb JTAG/OpenPCD debug
 - LLVM/Clang
 - Linux and Windows dev environment
 - Verification Suite
- RTG4 support
 - Soft RISC-V IP is free of charge
 - Preliminary IP is running at 70 MHz in RT4G150 "-1"
 - Sample RISC-V project for RTG4 dev kit available now on <u>GitHub website</u>
 - For details, refer to <u>RISC-V website</u>
- See our RTG4 RISC-V demo!







ARM Cortex M1 in RTG4

- ARM Cortex M1
 - 32-bit RISC microcontroller
 - Supported by ecosystem from ARM and third-party vendors



- IP available now on MSCC <u>website</u>: <u>End User Licensing Agreement (EULA)</u> must be completed in order to download IP
 - Uses DDR controller, SPI, UART, AHB to SRAM, and timer peripherals
 - Performance targeting RT4G150, Dash-1 speed grade

Design	RTG4 LUT	RTG4 DFF	RTG4 LSRAM Blocks	RTG4 uSRAM Blocks	MHz
ARM Cortex M1	11,600 (7.7%)	6,900 (4.5%)	2 (1.0%)	128 (61%)	50



Cobham Gaisler LEON3FT and LEON4FT for RTG4

- LEON3FT and LEON4FT are available for RTG4 – also support IGLOO2 and SmartFusion2 for prototyping
- Users select between built-in RTG4 LSRAM ECC or technology-agnostic fault-tolerance
- Bridges to optionally use Microsemi IP such as FDDR memory controller and SerDes IP
- Ready-made template designs, easily adapted. Bitstreams available: <u>www.gaisler.com/LEON-RTG4</u>
- Supported by the same software environment as existing LEON3FT and LEON4FT microprocessor devices
 - GCC and LLVM

) Microsemi

- RTEMS, VxWorks, Linux, Bare-C
- GRMON3, MKPROM2
- Validated in radiation tests. More to come during 2018.



Design	RTG4 4L	_UT	RTG4 DFF	L	RTG4 SRAM	MHz
LEON3 tiny, 2 windows, no cache	< 2% of	devi	ce resources	0		80
LEON3FT	14.9k	5.9k	ζ.	39		50
LEON4FT	16.2k	6.4k	ζ.	38		50
LEON3FT with FPU	23.8k	8.0k		39		50
LEON4FT with FPU	25.1k	8.4k		38		50

LEON3FT and LEON4FT configurations with 16 KiB D-cache and 16 KiB I-cache, including instruction trace buffer support (High-Performance LEON configuration). Makes use of RTG4 built-in ECC for SRAM.

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Other RTG4 IP Cores

- 1553 and PCIF—available now from Microsemi
- TSE and SGMII—available now from Microsemi
- JESD204B TX and RX—available now from Microsemi
- SpaceWire
 - STAR-Dundee IP available now
- SpaceFibre
 - STAR-Dundee IP available now, multi-lane operation at 3.125 Gbps per lane
- LEON3-FT and LEON4-FT
 - Cobham Gaisler IP available now
- Serial RapidIO
 - IP vendor evaluation in progress Contact Microsemi for details





Cobham Gaisler AB



Demo Platforms, Ref Designs, Eval Kits

- Microsemi Demos
 - LX7720 plus RTG4 motor control demo
 - LX7730 plus RTG4 telemetry demo
 - SA50 DC-DC Module for RTG4 Power supply demo
 - RTG4 with camera video processing demo
 - RTG4 in-flight reconfiguration demo w/ RISC-V
 - Space Development Platform
- Partner Demos

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- 3D-Plus memory with RTG4
- Cypress memory with RTG4
- Star Dundee SpWi and SpFi with RTG4
- Gaisler Leon3 with RTG4
- TI ADC with RTG4
- Blue Pearl CDC analysis tool RT3P and RTG4

See our RTG4 / RISC-V / LX7730 Demo



RTG4 Radiation Summary

Total Ionizing Dose	Stays within parametric limits > 125 Krad (Si)			
Single Event Latch-Up	No failure at facility limit of 103 MeV-cm ² /mg, 100 °C			
Configuration Upset	No failure at facility limit of 103	MeV-cm ² /mg, 100 °C		
Flip-Flop Single Event Upset	2.6E-12 errors/bit-day, GEO sol	lar minimum, 1 MHz		
LSRAM Single Event Upset	2.0E-7 errors/bit-day,1.1E-11 errors/bit-day,GEO solar min (no EDAC)GEO solar min (with EDAC)			
uSRAM Single Event Upset	3.1E-8 errors/bit-day, GEO solar min (no EDAC)	2.7E-13 errors/bit-day, GEO solar min (with EDAC)		
Low Eart	Highly Elliptical Earth Orbit Mid Earth Orbit Mid Earth Orbit Geosynchronous Earth Orbit	pace		



RTG4 Radiation Effects Update

Test	Environment	Test Schedule	Status
Fabric, SRAM and PLL SEE	Proton	Complete	Available on request
SERDES SEE	Heavy Ion	July 2018	Preliminary data to be presented at SpaceWire 2018; further testing in July 2018
In-Beam Programming	Heavy Ion	Complete	Presented at RADECS 2017 and SEE Symposium 2017
PLL SEE	Heavy Ion	July 2018	Preliminary data available; further testing in May 2018
Fabric DDR Controller SEE	Heavy Ion	July 2018	Testing in July 2018
MSIO SEE	Heavy Ion	May 2018	Testing in May 2018
TID (leakage current and propagation effects)	Gamma, X-ray	Complete (X-ray) Ongoing / per wafer lot (Gamma)	Presented at RADECS 2017 Posted on Microsemi web site
TID (retention effects)	Gamma, HTOL	Complete	Presented at NSREC 2016 and NSREC 2017

Contact Microsemi for reports

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Programs Baselining RTG4





RT FPGA Examples in Remote Sensing Payload



- RTG4 complements existing Microsemi Radiation Tolerant FPGAs
- Expected availability of RTSX-SU and RTAX FPGAs exceeds 10 years

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RTG4 Availability and Qualification Schedule

- QML class Q qualification: <u>Completed!</u>
 - RTG4 B- and E-flow can be ordered to DLA SMD part number
 - DLA SMD part numbers on Microsemi web site
- QML class V qualification: expected August 2018
- MIL-STD-883 Class B Qualification: Completed
- RT4G150 PROTO FPGAs: Now
- RT4G150 development kit: Now
- CG1657 B/E/EV-flow flight units: Available to lead time now
- CG1657 daisy chain packages: Now
- CQ352 B-flow flight units: July 2018
- CQ352 eng models: Available to lead time now



CQ352



RT4G150-

CG1657

RTG4 Development Kit

Delivering A Comprehensive Space Portfolio

Radiation-Tolerant FPGAs	High Performance, High Density, Low Power TID up to 300 Krad, SEL Immune RTG4 FPGAs up to 300 MHz and 150K LE RTProASIC3, RTAX and RTSX-SU QML Qualified
Rad-Hard Mixed Signal Integrated Circuits	Telemetry and Motor Control Space System Managers High Side Drivers Regulators and PWMs Extensive Custom IC Capability
Space Qualified Oscillators	Ovenized Quartz Oscillators Hybrid Voltage Controlled and Temperature Compensated Crystal Oscillators Cesium Clocks
Rad-Hard Power Solutions	Rad-hard JANS Diodes, Bi-Polar Small Signal Transistors, and MOSFETs Rad-hard Isolated DC-DC Converter Modules Custom Power Supplies 2 W to > 5 KW Point of Load Hybrid Solutions Electromechanical Relays
Space Screening capability on RF Products	Surface Acoustic Wave (SAW) Filters Packaged and Chip Si Diodes Si Bipolar Transistors GaAs pHEMT MMICs
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Mixed Signal ICs: Weight and Board Space Reduction





- LX7730 Telemetry Controller
- LX7720 Motor / Position Controller
- AAHS298B High Side Drivers
- LX7710 Diode Arrays
- Custom Mixed Signal Integrated Circuits



Microsemi Analog Mixed Signal ICs for Space Applications

Part Number	Description	Status	SMD
In Production			
LX7730	RT telemetry controller	QML certified Q & V 132 L CQFP	5962-1721901QXC
AAHS298B	RT 8 channel high side driver	QML certified Q & V 20 L CSOIC flat leads 20 L CSOIC formed leads	5962-1523101QYC,VYC 5962-1523101QXC,VXC
LX7710	RT 8 pair diode array	QML certified Q & V 20 L CSOIC formed leads	5962-1621001QXC, VXC
Custom	Various	In Flight	N/A (QML-Q and QML-V screening)
In Qual			
LX7720	RT motor/position controller	Sampling now Seeking QML V & Q	TBD



Space Power Products

Product Family	Key Differentiation		
Radiation-Hardened Isolated DC-DC Converters	 Highest output power and efficiency Shortest lead times 	High Efficiency	Output Power
Radiation-Hardened Power Discretes: JANS Diodes, Bi-Polar Transistors, MOSFETs	 Broadest JANS QPL portfolio Low Dose Rate guaranteed bipolar transistors 	Broadest Portfolio	Shortest Lead Times
Radiation-Hardened Hybrids: Linear and Switching	 DLA MIL-PRF-38534-certified facility Highly integrated for optimal power footprint 	Highly Integrated	DLA Certified Facility
High-Voltage Electromechanical Relays	Highest reliabilityExtensive heritage in space	Highest Reliability	Extensive Heritage



Space Oscillators and Atomic Clocks

- Eliminate the need for SCD Creation
- Use Microsemi's Hi-Rel Standard documentation for Space Applications



Space CSAC (released March 2018)

- Radiation Tolerance: 20krad(Si) TID, no SEL to 64 MeVcm²/gm
- Targeting short duration LEO applications (COTS product)
- Low size, weight and power

Key Specifications:

- Nominal Frequency: 10 MHz
- Power Consumption: <120 mW steady-state @ +25C
- Volume: <17 cc
- Temp Stability: ±5.0E-10
- Operating Temp Range: -10 to +70C
- Aging Rate: <9.0E-10/month (typical)
- Warm-up Time: 3 min
- 1PPS disciplining



Source: NASA/JPL-Caltech





Microsemi Space Legacy – 60 Years, and Counting!



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Your Partner for Space Technology



- Leadership in space
- Leveraging our product breadth
- Innovative new products
- Focused on growth applications





Thank You



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